



1.0 **SCOPE**

This specification defines the functionality as well as the mechanical and electrical interfaces for the Molex Family of MXMag Magnetic Jacks.

2.0 PRODUCT DESCRIPTION

The MXMag magnetic connector offers a simple solution for integrating Ethernet magnetics and the RJ-45 connector interface into one integrated package with guaranteed signal integrity, Fast and Gigabit Ethernet, common mode termination and EMI shielding. The connector is available in 0.85" deep Inverted profile, 0.85" deep Standard profile and 1" deep profile versions. The connector includes up to two LED's per port.

3.0 PRODUCT NAME AND SERIES NUMBER

Tr	ay	Таре	& Reel	
3.3mm PHY Pin	1.8mm PHY Pin	3.3mm PHY Pin	1.8mm PHY Pin	Description*
93461	93741	93753	93765	0.85" 4C FE STD
93462	93742	93754	93766	0.85" 4C FE INV
93463	93743	93755	93767	1" 4C FE INV
93626	93744	93756	93768	0.85" 8C GIG STD
93627	93745/94011	93757	93769	0.85" 8C GIG INV
93628	93746	93758	93770	1" 8C GIG INV
93634	93747	93759	93771	0.85" 6C FE STD
93635	93748	93760	93772	0.85" 6C FE INV
93636	93749	93761	93773	0.85" 12C GIG STD
93637	93750	93762	93774	0.85" 12C GIG INV
93638	93751	93763	93775	1" 6C FE INV
93639	93752	93764	93776	1" 12C GIG INV

MXMag Single Port Series Connector

MXMag Dual Port Series Connector

Tr	ay	Tape	& Reel	
2.7 mm PHY Pin	2.2 mm PHY Pin	2.7 mm PHY Pin	Description*	
93824	93828	93832	93836	DP 4C FE INV
93825	93829	93833	93837	DP 6C FE INV
93826	93830	93834	93838	DP 8C GIG INV
93827	93831	93835	93839	DP 12C GIG INV

* 0.85" & 1" refer to connector depth, C = cores, FE = Fast Ethernet, GIG = Gigabit Ethernet, INV = Inverted / Tab-Up, STD = Standard / Tab-Down, DP = Dual Port

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4.0 FEATURES

Range of Fast & Gigabit Ethernet magnetic options Integrated Common Mode Termination Circuitry Operating Temperature range: SEE RELEVANT SALES DRAWINGS 2250 V DC isolation Integrated LED options Options available for Reflow or Wave soldering process

5.0 SAFETY AGENCY APPROVALS

UL File Number......E177474

This product is designed as an SELV CIRCUIT and is considered to be powered up by a TELECOMMUNICATION CABLE OR A CABLE DISTRIBUTION SYSTEM. For any other power supply, the requirements of IEC 60950-1 must be taken into consideration.

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6.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

Molex sales drawing

See relevant sales drawing for information on dimensions, materials, markings and product offerings.

Plating

Contact Surface: Palladium Nickel With Gold Flash: Post plate 0.05 μm Min Gold Flash over 1.00 μm Min Palladium Nickel in contact area, 1.90 μm Min pure Tin in tail area, both over 1.270 μm Min Nickel overall.

PHY Terminals: 1.25 µm Min Nickel.

Shield: 1.27 μ m Min Nickel, solder tabs post plated with 1.27 μ m Min Tin

Molex Packaging Spec

See relevant Sales Drawings

Applicable standards

IEC 60603-7

IEC 60603-7-1

TIA-1096-A

EIA-364-65

IEC 60951-1

IEEE802.3

LED Terminal Pinout

The Magnetic Jack has on-board LEDs that can be controlled directly. Each Magnetic Jack has two LED positions per port with up to two different colours (single or bicolour) per position. The bicolour LEDs are bipolar. Colour change is achieved by reversing voltage using an external switch or relay. Note that the LEDs need external current limitation and voltage adjustment according to the LED characteristics. See LED Pin out examples below.

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PRODUCT SPECIFICATION

LED Electrical Characteristics

The following table contains the electrical characteristics for the LED and the LED terminals on the Magnetic Jack.

All LEDs are low power LEDs according to IEC 62471 /exempt group.

			Without 250 ΩWith 250 ΩResistorResistor		250 Ω istor				
Parameter	Symbol	Colour	Min	Max	Min	Max	Unit	Condition	
Formuland		Green	1.8	2.4	8	10			
Forward	V_{f}	Orange	1.8	2.4	8	10	V		
voitage		Yellow	1.8	2.4	8	10		@lf = 20 m∆	
Dominant Wayolongth	λD	Green	567	575	567	575		@11 – 20 MA	
		Orange	600	612	600	612	nm		
wavelength		Yellow	585	595	585	595			
Forward		Green	5	25	5	25			
Current	lf	Orange	5	25	5	25	mA	N/A	
Current		Yellow	5	25	5	25			
		Green	5	10	5	10			
Intensity	v	Orange	5	10	5	10	mcd	@lf = 10 mA	
intensity		Yellow	5	10	5	10		-	

6.1 ABSOLUTE MAXIMUM RATINGS (TABLE 1)

Temperature Ranges	
Operating	SEE RELEVANT SALES DRAWINGS
Non-operating (No condensation)	-55°C to +85°C
Maximum Current	
Per RJ45 contact	0.5 A

Table 1 – Absolute Max Ratings

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7.0 TEST SCHEDULES

The following tests specify the characteristics to be checked and the requirements to be fulfilled. This test sequence is based on IEC 60603-7 and EIA-364-1000. Where required Molex has modified testing based on the customers' requirements and changes required to accommodate custom requirements of the connector.

For a complete test sequence, a minimum of 90 specimens are needed. Test Group EP & CZ is customised by Molex for this sequence. All connectors in each group shall undergo the following tests as described in the sequence given.

All the test group specimens shall be subjected to the preliminary group P tests in the following sequence.

Test group P

P1 VISUAL INSPECTION IEC 60512-1-1 Test 1a There shall be no defects t would impair normal operation P2 INITIAL CONTACT RESISTANCE (LOW LEVEL) Mated connectors: Max test voltage 20 mV DC or AC peak, test current 100 mA DC or AC peak, Arrangement acc. IEC 60603-7 Section 7.3 5mΩ MAXIMUM [Initial] P3 INSULATION RESISTANCE (PHY TERMINALS TO SHIELD) Test voltage 100 V DC ± 15V Method A mated connectors 500 MΩ Minimum P4 HI-POT (VOLTAGE PROOF / ISOLATION) Z250 V DC for 60 seconds. (Between PHY pins + shield to RJ45 Terminals) 500 V DC (LEDs to Shield) 2250 V DC (LEDs to RJ45 Terminals) (IEC 60950-1: 2001 Sub-clause 5.2.2.) No breakdown REVISION: ECM.INFORMATION: ECM:: TITLE: MXMAG PRODUCT SPECIFICATION St MXMAG PRODUCT SPECIFICATION	- P	TEST PHASE	DESCRIPTION	TES	T CON	DITION		REQUIR	EMENT	
P2 INITIAL CONTACT RESISTANCE (LOW LEVEL) Mated connectors: Max test voltage 20 mV DC or AC peak, test current 100 mA DC or AC peak, test current 1		P1	VISUAL INSPECTION	IEC	60512-	1-1 Test 1a		There shall be would impair no	no defect ormal ope	s that eration
IEC 60512-2-1 Test 2a P3 INSULATION RESISTANCE (PHY TERMINALS TO SHIELD) Test voltage 100 V DC ± 15V Method A mated connectors P4 HI-POT (VOLTAGE PROOF / ISOLATION) 2250 V DC for 60 seconds. (Between PHY pins + shield to RJ45 Terminals) No breakdown P4 HI-POT (VOLTAGE ISOLATION) 2250 V DC for 60 seconds. (Between PHY pins + shield to RJ45 Terminals) No breakdown E ECM.INFORMATION: EC.No: 602124 DATE: IITLE: MXMAG PRODUCT SPECIFICATION SH 9		P2	INITIAL CONTACT RESISTANCE (LOW LEVEL)	Mate Max test Arra Secti	ed conr test vo current ngeme on 7.3	nectors: Itage 20 mV DC or AC pe 100 mA DC or AC peak nt acc. IEC 60603-7	eak,	5 n MAXII [Init	ηΩ MUM ial]	
P3 INSULATION RESISTANCE (PHY TERMINALS TO SHIELD) Test voltage 100 V DC ± 15V Method A mated connectors 500 MΩ Minimum P4 HI-POT (VOLTAGE PROOF / ISOLATION) 2250 V DC for 60 seconds. (Between PHY pins + shield to RJ45 Terminals) No breakdown VOLTAGE P4 HI-POT (VOLTAGE PROOF / ISOLATION) 2250 V DC (LEDs to Shield) 2250 V DC (LEDs to RJ45 Terminals) (IEC 60950-1: 2001 Sub-clause 5.2.2.) No breakdown				IEC 6	60512-2	2-1 Test 2a				
Image: Product structure Image: Product		P3	INSULATION RESISTANCE (PHY	Test v mate	voltage ed conr	100 V DC ± 15V Method nectors	A	500 MΩ I	Minimum	
P4 HI-POT (VOLTAGE PROOF / ISOLATION) 2250 V DC for 60 seconds. (Between PHY pins + shield to RJ45 Terminals) No breakdown P4 PROOF / ISOLATION) 500 V DC (LEDs to Shield) 2250 V DC (LEDs to RJ45 Terminals) No breakdown (IEC 60950-1: 2001 Sub-clause 5.2.2.) (IEC 60950-1: 2001 Sub-clause 5.2.2.) No breakdown REVISION: ECM INFORMATION: EC No: 602124 DATE: 2019/01/25 TITLE: MXMAG PRODUCT SPECIFICATION SH			SHIELD)	IEC	60512-	3-1: Test 3a				
REVISION: ECM INFORMATION: TITLE: E EC No: 602124 MXMAG PRODUCT SPECIFICATION DATE: 2019/01/25 9		P4	HI-POT (VOLTAGE PROOF / ISOLATION)	2250 V DC for 60 seconds. (Between PHY pins + shield to RJ45 Terminals) 500 V DC (LEDs to Shield) 2250 V DC (LEDs to RJ45 Terminals)			5)	No breakdown		
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	Test	group	AP
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TEST PHASE	TITLE			SEVERITY	REQU	IREMENTS		
AP 1	INSERTION AND WITHDRAWAL FORCES	Connector locking device depressed. PER IEC 60512-13-2, Test 13b			Insertion Withdrawa	Insertion force 30 N max Withdrawal force 30 N ma		
AP 2	EFFECTIVENESS OF CONNECTOR COUPLING DEVICE.	Rate 44 PER	of load I.5 N/s IEC 60	application Max 512-15-6, Test 15f	50 N	l for 60s ± 5	S	
AP 3	RAPID CHANGE OF TEMPERATURE	-40°C to 85°C Mated connectors 25 cycles I = 30 min recovery time 2 h						
AP 4	INSULATION RESISTANCE (PHY terminals to shield)	PER Test v 100V metho IEC 6	IEC 60 voltage ±15 V od a, m	068-2-14 DC nated connectors 3-1, Test 3a, Method a.	P	ER P3		
AP 5	CONTACT RESISTANCE	PER P2			10 mΩ ma froi	10 mΩ maximum change from initial		
AP 6	VOLTAGE PROOF	PER P4			P	PER P4		
AP 7	VISUAL EXAMINATION	PER P1			P	PER P1		
AP 8	CYCLIC DAMP HEAT	21 cycles low temperature 25°C high temperature 65°C cold sub-cycle –10°C humidity 93 % Half of the samples in mated state Half of the samples in un-mated state						
AP 9	CONTACT RESISTANCE			PER P2	10 mΩ ma froi	ximum cha m initial	inge	
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Test gr	oup AP (continued).		
TEST PHASE	TITLE	SEVERITY	REQUIREMENTS
AP 10	INSERTION AND WITHDRAWAL FORCES	PER AP1	PER AP1
AP 11	EFFECTIVENESS OF CONNECTOR COUPLING DEVICE.	Rate of load application 44.5 N/s Max PER IEC 60512-15-6, Test 15f	50 N for 60 s ± 5 s
AP 12	VISUAL EXAMINATION	PER P1	PER P1
AP 13	SOLDERABILITY	Solder Bath 245 °C ± 3 °C Immersion Time 3.0 s ± 0.3 s PER IEC 60068-2-20 Test Ta Method 1	Solder area will have a minimum of 95% solder coverage.
AP 14	RESISTANCE TO SOLDERING HEAT	For wave solder connectors: Temperature: 260 °C ± 3 °C Immersion Time: 10 s ± 1 s PER IEC 60068-2-20 Test Tb Method 1 For recommended Reflow Profile (See Section 8.0)	Appearance: No Damage.
AP 15	VOLTAGE PROOF	PER P4	PER P4

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Test group BP

TEST PHASE	TITLE	SEVERITY	REQUIREMENTS
BP 1	LOCKING DEVICE MECHANICAL OPERATIONS.	5,000 operations	After the specified number of operations, the specimens shall show no visual indication of fatigue or stress cracking of the locking device.
BP 2	HI-POT (VOLTAGE PROOF / ISOLATION)	PER P4	No breakdown
BP 3	CONTACT RESISTANCE	PER P2	10 m Ω maximum change from initial
BP 4	DURABILITY	EIA-364-09 (perform the rated number of unplug/plug cycles. retention features, such as latches, should not be deactivated.) 2,500 cycles	no evidence of physical damage
BP 5	CONTACT RESISTANCE	PER P2	10 m Ω maximum change from initial
BP 6	HI-POT (VOLTAGE PROOF / ISOLATION)	PER P4	No breakdown

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Test group CP

TEST PHASE	TITLE	SEVERITY	REQUIREMENTS
CP 1	VIBRATION	f = 10 Hz to 500 Hz, Amplitude: 0.35 mm Accel 50m/s ² 10 sweeps / axis (3axis) Time 2 hours/axis measurement points per section 7.0 (For arrangement,See IEC 60603-7, 7.3) PER IEC 60512-6-4, Test	Discontinuities 0.1µs maximum.
CP 2	CONTACT RESISTANCE No disturbance of the free connector to fixed connector electrical connections, between vibration test and contact resistance measurement	PER P2	10 m Ω maximum change from initial
CP 3	INSULATION RESISTANCE (PHY terminals to shield)	PER P3	PER P3
CP 4	VISUAL EXAMINATION	PER P1	PER P1

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Test group DP

TEST PHASE	TITLE	SEVERITY	REQUIREMENTS
DP 1	ELECTRICAL LOAD AND TEMPERATURE	500 h 70°C Recovery period 2 h PER IEC 60512-9-2, Test 9b	1.6 A shield contacts 5 connectors, no current 5 connectors 0.5 A per RJ45 contact.
DP 2	INSULATION RESISTANCE (PHY terminals to shield)	PER P3	PER P3
DP 3	VOLTAGE PROOF	PER P4	PER P4
DP 4	VISUAL EXAMINATION	PER P1	PER P1
DP 5	CONTACT RESISTANCE	PER P2	10 m Ω maximum change from initial
DP 6		N/A	
DP 7	GAUGING CONTINUITY	All signal contacts and screen/specimens	0.1 μs maximum



Test Group EP

TEST PHASE	TITLE	г	EST CONDITION
EP 1	Insertion loss (dB)	Mated Connectors	
EP 2	Return loss (dB)	Mated Connectors	
EP 3	NEXT loss (dB)	Mated connectors, pair to pair	See Relevant Sales Drawings for Part specific Transmission Values
EP 4 CMR (dB)		Mated Connectors	
EP 5	OCL (µH min)	Wire Side	

Test group FP

TEST PHASE	TITLE	SEVERITY	REQUIREMENTS	
FP 1	SURGE TEST Test no. ITU_T K.20:2000	Mated connectors, Table 2a /2b, Basic test level Tests 2.1.1a, 2.1.1b, 2.1.3, 2.2.1a	Test 2.1 & 2.2: Acceptance criteria A per ITU-T K.44, clause 9	
FP 2	INSULATION RESISTANCE (PHY terminals to shield)	PER P3	PER P3	
FP 3	VISUAL EXAMINATION	PER P1	PER P1	

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Test Group GP

TEST PHASE	TITLE	SEVERITY	REQUIREMENTS
GP1	HIGH TEMPERATURE (DRY HEAT)	336 h 70°C Recovery period 2 h PER IEC 60068-2-2, Test Bb	Mated 10 m Ω maximum change from initial
GP2	CYCLIC DAMP HEAT	21 cycles low temperature 25°C high temperature 65°C cold subcycle –10°C humidity 93 % Half of the samples in mated state Half of the samples in unmated state	10 m Ω maximum change from initial

Test group AZ

TEST PHASE	TITLE	SEVERITY	REQUIREMENTS
AZ1	HIGH TEMPERATURE (DRY HEAT)	Mate connectors; expose to: 96 hours at 85°C ± 2°C PER IEC 60068-2-2, Test 9b	Use Molex plug 500602-0819
AZ 2	CONTACT RESISTANCE	PER P2	10 m Ω maximum change from initial

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Test group CZ (Use Molex Plug 500602-0819)

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TEST PHASE	TITLE	SEVERITY	REQUIREMENTS
CZ 1	CONTACT RESISTANCE	PER P2	$5 \text{ m}\Omega$ maximum change from initial
CZ 2	1.0 MECHANICAL OPERATIONS 2.0	Mate/un-mate connectors 20 cycles, at a maximum rate of 10mm/s maximum. Rest 1s (when mated and when unmated) Locking device inoperative.	No Evidence Of Physical Damage.
CZ 3	TEMPERATURE LIFE PER EIA-364-17, METHOD A (TEMPERATURE AND DURATION PER EIA-364- 1000, TABLE 9, 60°C FOR 10YEARS).	Mate Connectors 105°C for 72 hours	Use Molex plug 500602-0819
CZ 4	CONTACT RESISTANCE	PER P2	10 m Ω maximum change from initial
CZ 5	FLOWING MIXED GAS CORROSION PER EIA 364-65 CLASS IIA	1/2 samples mated for 336 hours, ½ samples unmated for 240 hours, then mated for final 96 hours. (do not place unmated plugs in chamber).	
CZ 6	CONTACT RESISTANCE	PER P2	10 m Ω maximum change from initial
CZ 7	THERMAL DISTURBANCE	Mate Connectors 10 cycles of 15°C ± 3°C to 85°C ± 3°C/ dwell 30 minutes at each temp	
CZ 8	CONTACT RESISTANCE	PER P2	10 m Ω maximum change from initial
CZ 9	RESEATING	Manually unplug/plug the connector or socket. perform 3 such cycles.	No evidence of physical damage
CZ 10	CONTACT RESISTANCE	PER P2	10 m Ω maximum change from initial
CZ 11	VISUAL EXAMINATION	PER P1	PER P1

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PRODUCT SPECIFICATION

8.0 SOLDERING CONDITIONS.

Recommended

REFLOW SOLDERING SIMULATION PEAK PROFILE REFLOW AT 260 °C

DESCRIPTION	REQUIREMENT
Solder Type	None
Solder Flux Type	None
Paste Flux Type	None
Average Ramp Rate	3 °C/second maximum
Preheat Temperature	150 °C minimum; 200 °C maximum
Preheat Time	60 to 180 seconds
Ramp to Peak	3 °C/second maximum
Time over Liquidus (217 °C)	60 to 150 seconds
Peak Temperature	260 °C +0/-5 °C
Time within 5 °C of peak	20 to 40 seconds
Ramp – Cool Down	6 °C/second maximum
Time 25 °C to Peak	8 minutes maximum

Table 2 – Reflow simulation.



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9.0 PACKAGING

Parts shall be packaged to protect against damage during handling, transit and storage. See relevant Packaging specifications.

10.0 ESD PROTECTION

To avoid damage by an electrostatic discharge while installing the connector, ESD packaging has been used. For more details see relevant Packaging specifications.

11.0 GAUGES AND FIXTURES

Arrangement for contact resistance test: Arrangement acc. IEC60603-7 section 7.2

Arrangement for vibration test: Arrangement acc. IEC60603-7 section 7.3

12.0 QUALITY ASSURANCE PROVISIONS

The applicable Molex Inspection plan specifies the sampling acceptable quality level to be used. Dimensional and functional requirements shall be in accordance with applicable product drawings and this specification.

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13.0 APPENDIX B

The norms and standards cited in the following sections are applicable.

Test	Description
	Environmental testing – Part 2-14: Tests – Test N: Change of
	Iemperature
	Environmental testing – Part 2-2-: Tests – Test T: Test methods for
	solderability and resistance to soldering heat of devices with leads
	Environmental testing – Part 2-38: Tests – Test Z/AD: Composite
	temperature/humidity cyclic test
	Environmental testing - Part 2: Tests - Test Ke: Flowing mixed gas
	corrosion test
	Environmental testing - Part 2-78: Tests; Test Cab: Damp heat,
	steady state
0-	Part 2-1: Electrical continuity and contact resistance tests; Test 2a:
Za	Contact resistance - Millivolt level method
3a	Part 3-1: Insulation tests; Test 3a: Insulation resistance
40	Part 6: Climatic tests and soldering tests: Test 12a: Solderability.
12a	wetting, solder bath method.
6c	Part 6-3: Dynamic stress tests: Test 6c: Shock
	Connectors for electronic equipment - Tests and measurements -
6d	Part 6-4: Dynamic stress tests - Test 6d: Vibration (sinusoidal)
9a	Part 9-1: Endurance tests - Test 9a: Mechanical operation
	Connectors for electronic equipment - Tests and measurements -
9b	Part 9-2: Endurance tests - Test 9b: Electrical load and
	temperature
	Part 13-2: Mechanical operation tests - Test 13b: Insertion and
13b	withdrawal force
	Connectors for electronic equipment – Tests and measurements
15f	Part 15 - Connector tests (mechanical) – Test 15f: Effectiveness
	of connector coupling devices
	Connectors for electronic equipment - Part 7: Detail specification
	for 8-way
	unshielded free and fixed connectors
	Connectors for electronic equipment - Part 7-1: Detail specification
	for 8-way
	shielded free and fixed connectors
	Information technology equipment – Safety – Part 1: General
	Requirements
	Standard for Ethernet
	Test - - 2a 3a 12a 6c 6d 9a 9b 13b 15f

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F	<u>EC No:</u> 602124		MXMAG PRODUCT SPECIFICATION					
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TIA 1096 A	Connector requirements for connection of Terminal Equipment to the telephone network
EIA-364-65	Mixed Flowing test procedure for electrical connectors contacts and sockets.
EIA-364-17	Temperature Life with or without Electrical Load Test Procedure for Electrical Connectors and Sockets
EIA-364-1000	Environmental Test Methodology For Assessing The Performance Of Electrical Connectors And Sockets

Table 3 – Standards Index.

Released Revision Control

Revision	Change	Person Responsible	ECN No:	Date:
2	Release post screen testing	D.Byrnes		
В	Product Testing	D.Byrnes	109228	03-Oct-2016
С	Edited Section AP13 Solderability and added Dual Port	DShea	169633	04-Oct-2017
D	Updated UL File Number	DShea	606445	02-Oct-2018
E	Updated Sections AP13 and AP14	DShea	602124	19-Dec-2018

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	DATE: 2019/01/25						
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